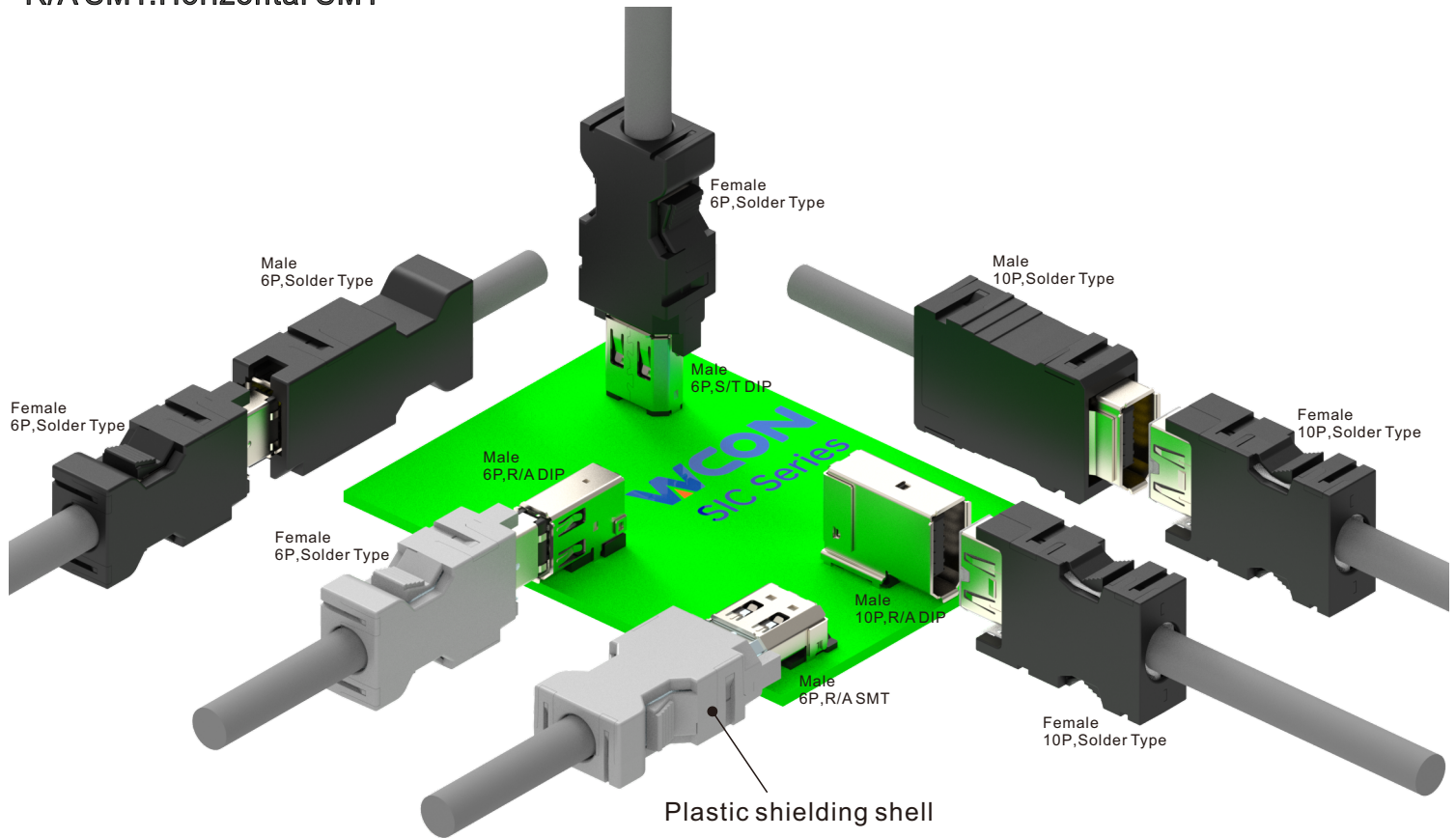


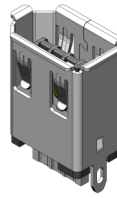
Board-Mounting  
S/T DIP:Vertical T/H  
R/A DIP:Horizontal T/H  
R/A SMT:Horizontal SMT



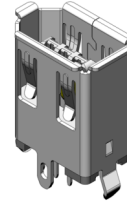


### SPECIFICATIONS

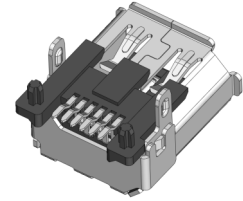
Current Rating: 1.0 AMP  
 Contact Resistance: 30mΩ Max.  
 Insulation Resistance: 100MΩ Min  
 Withstand Voltage: 500V AC/Minute  
 Operation Temperature: -40°C to +85°C  
 Contact Material: Phosphor Bronze  
 Contact Plating: Au And Sn Over Ni  
 Insulation Material: LCP+30%GF (UL94V-0)  
 Type: M



B6130-06MHSXDBNA1

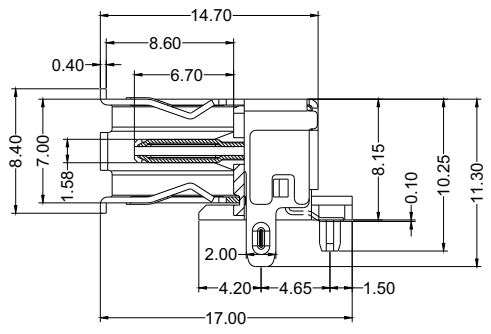
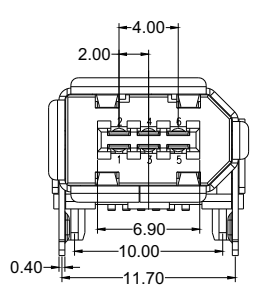
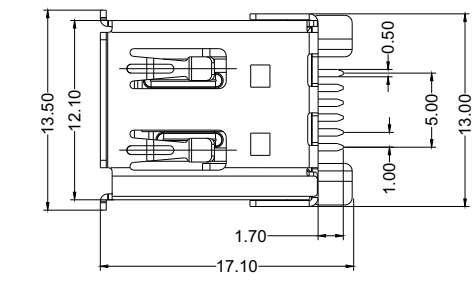
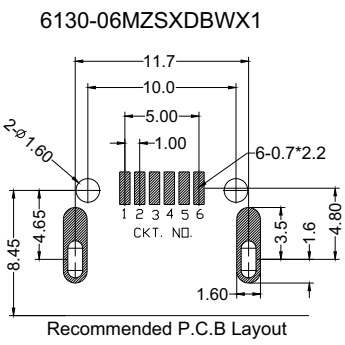
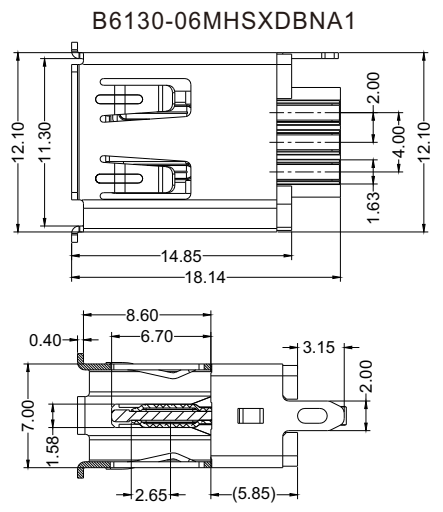
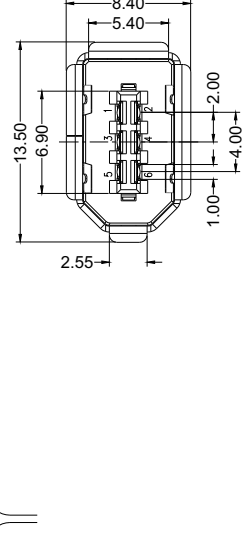
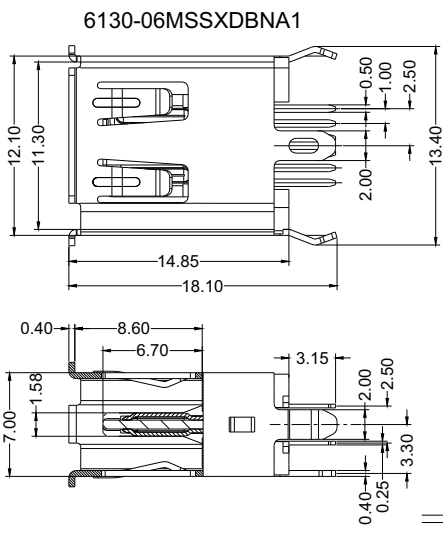
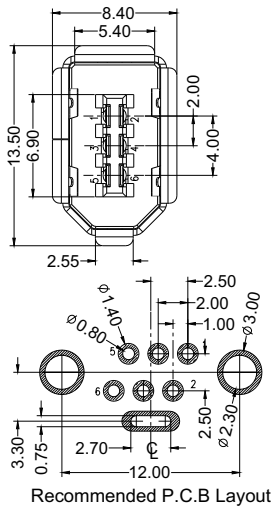


6130-06MSSXDBNA1



6130-06MZSXDBWX1

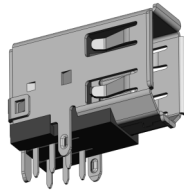
<b>6130 - 06</b>	<b>M</b>	<b>X</b>	<b>SX</b>	<b>D</b>	<b>B</b>	<b>N</b>	<b>A</b>	<b>1</b>
Positions 6	M: Male	Board-Mounting Z=R/A SMT S=S/T DIP H=Solder	Contact plating area S1=30U" Au/Tin S3=10U" Au/Tin S5=30U" Au/Tin		Color B=Black	N=W/O Post	Packaging A=Tray	



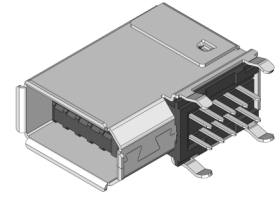


## SPECIFICATIONS

Current Rating:1.0 AMP  
 Contact Resistance:30mΩ Max.  
 Insulation Resistance: 100MΩ Min  
 Withstand Voltage: 500V AC/Minute  
 Operation Temperature: -40°C to +85°C  
 Contact Material:Phosphor Bronze  
 Contact Plating: Au And Sn Over Ni  
 Insulation Material:LCP+30%GF (UL94V-0)  
 Type:M



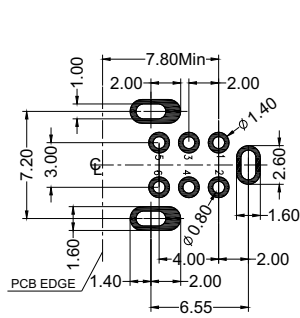
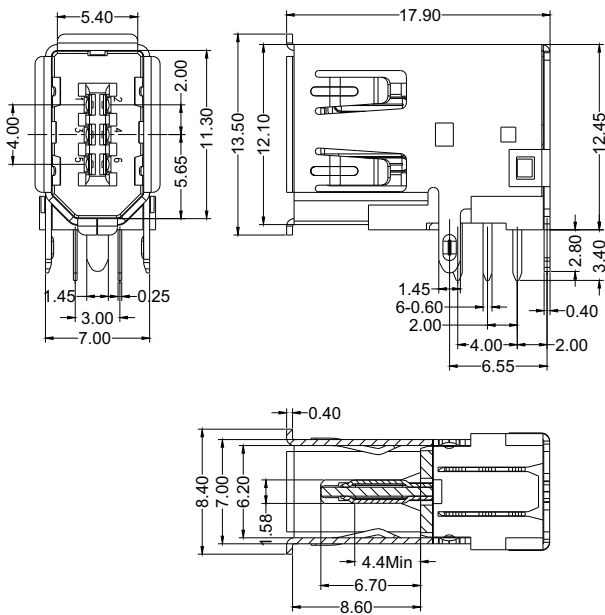
6130-06MDSXDBNA1



6130-10MDSXDBNA1

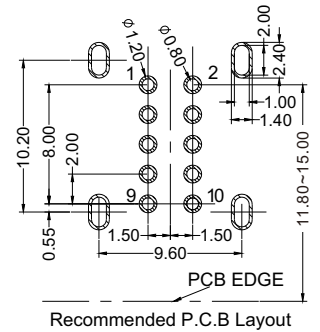
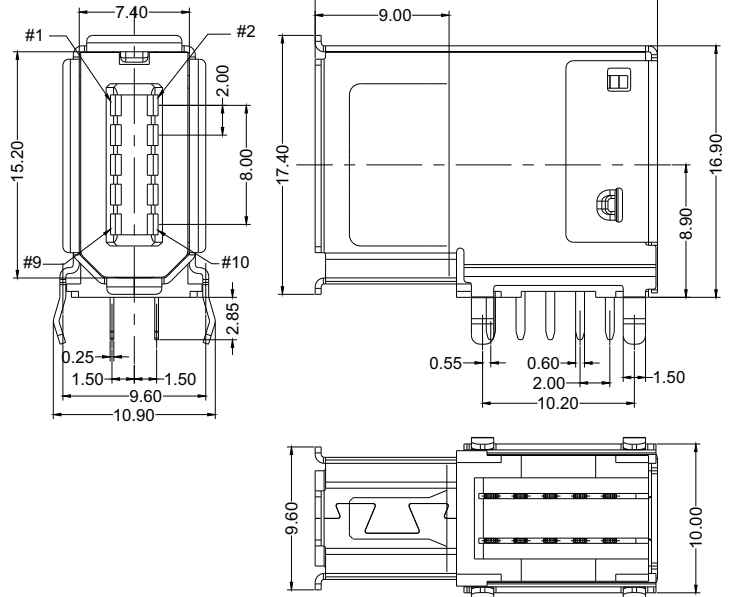
<b>6130</b>	-	<b>XX</b>	<b>M</b>	<b>X</b>	<b>SX</b>	<b>D</b>	<b>B</b>	<b>N</b>	<b>A</b>	<b>1</b>
		Positions 6,10	M:Male	Board-Mounting D=R/A DIP(Sider)	Contact plating area S1=3U" Au/Tin S3=10U" Au/Tin S5=30U" Au/Tin		Insulator Color B=Black	N=W/O Post	Packaging A=Tray	

6130-06MDSXDBNA1



Recommended P.C.B Layout

6130-10MDSXDBNA1

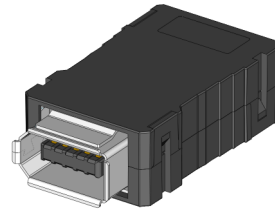


Recommended P.C.B Layout

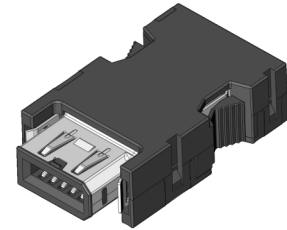


**SPECIFICATIONS**

Current Rating: 1.0 AMP  
 Contact Resistance: 30mΩ Max.  
 Insulation Resistance: 100MΩ Min  
 Withstand Voltage: 500V AC/Minute  
 Operation Temperature: -40°C to +85°C  
 Contact Material: Phosphor Bronze  
 Contact Plating: Au And Sn Over Ni  
 Insulation Material: LCP+30%GF (UL94V-0)  
 Type: M



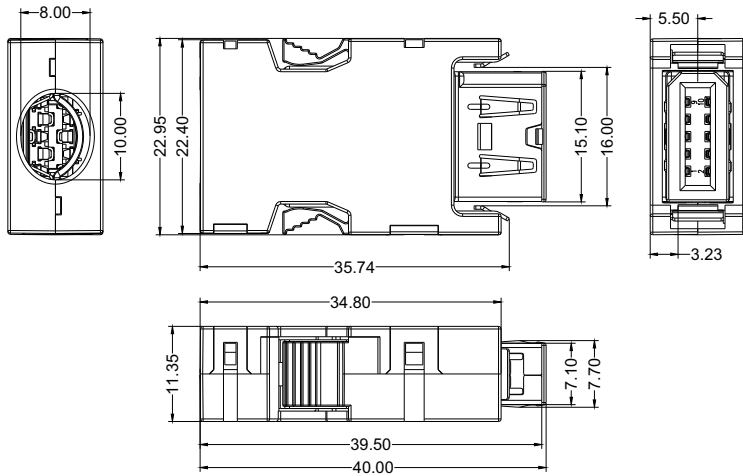
6131-10MSXMAGA1



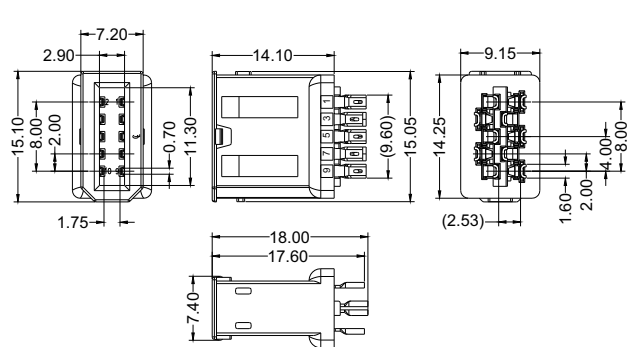
6131-10FS0MAGA1

<b>6131 - 10</b>	<b>X</b>	<b>SX</b>	<b>M</b>	<b>A</b>	<b>G</b>	<b>A</b>	<b>1</b>
Positions 10	M: Male F: Female	Contact plating area S1=3U" Au/Tin S3=10U" Au/Tin			Plastic Shell Color B: Black G: Grey	Packaging A=Tray	

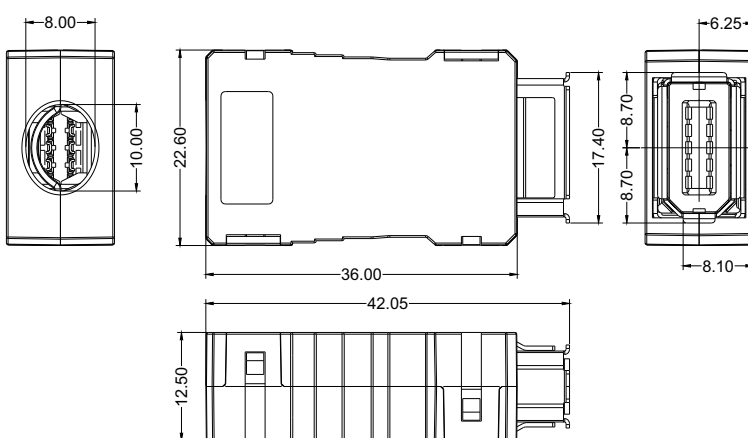
6131-10FXXMAGA1



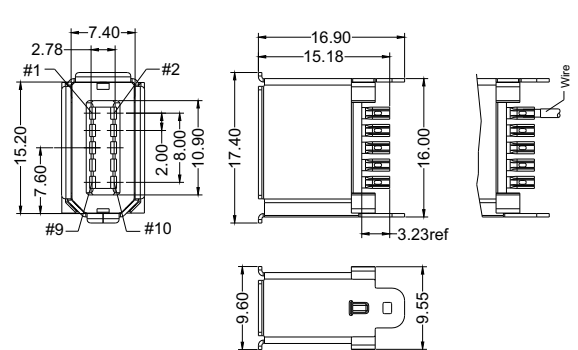
B6131-10FXXABA1



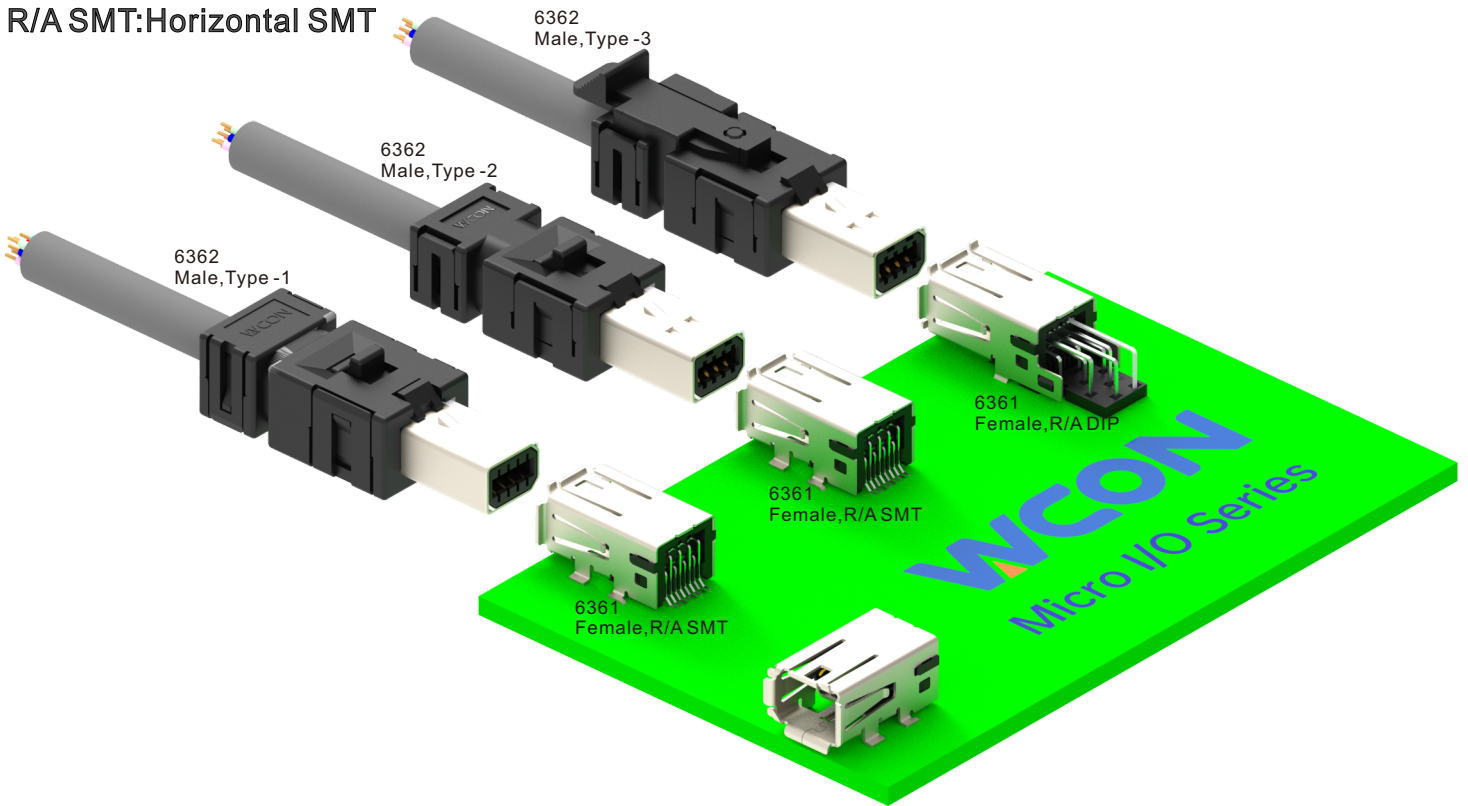
6131- 10 MXX MABA1



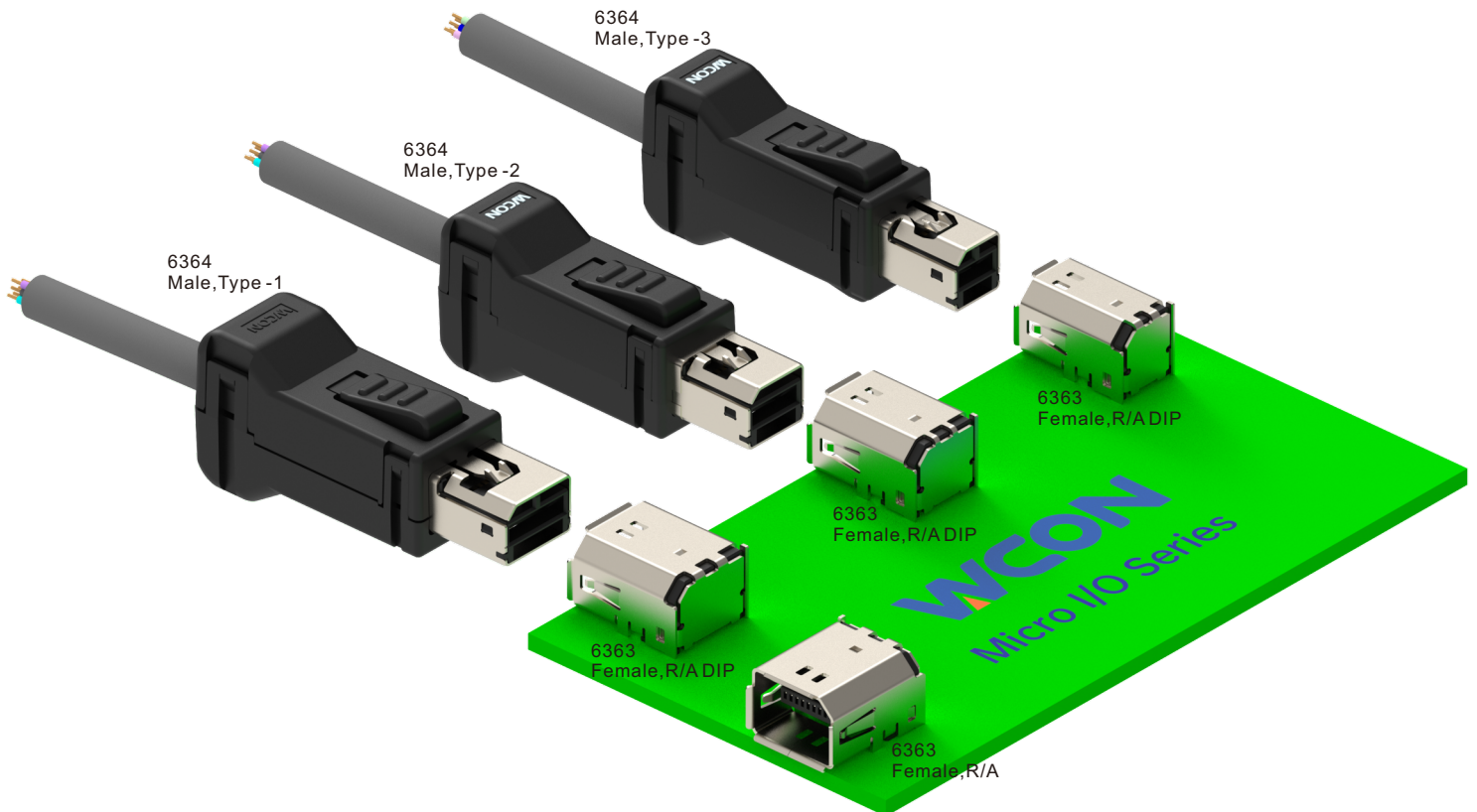
B6131-10M XX DBA1



Board-Mounting  
R/A DIP:Horizontal T/H  
R/A SMT:Horizontal SMT



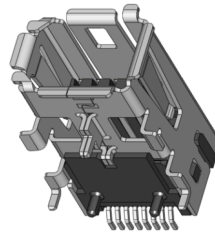
Board-Mounting  
R/A DIP:Horizontal T/H



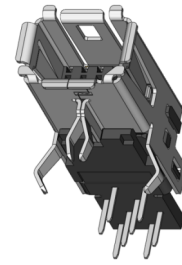


### SPECIFICATIONS

**Current Rating:**0.5 AMP  
**Contact Resistance:**40mΩ Max.  
**Insulation Resistance:** 500MΩ Min  
**Withstand Voltage:** 1000V AC/Minute  
**Operation Temperature:** -40°C to +85°C  
**Contact Material:**Copper Alloy  
**Contact Plating:**Au And Sn Over Ni  
**Insulation Material:**LCP+GF (UL94V-0)  
**Type:**T

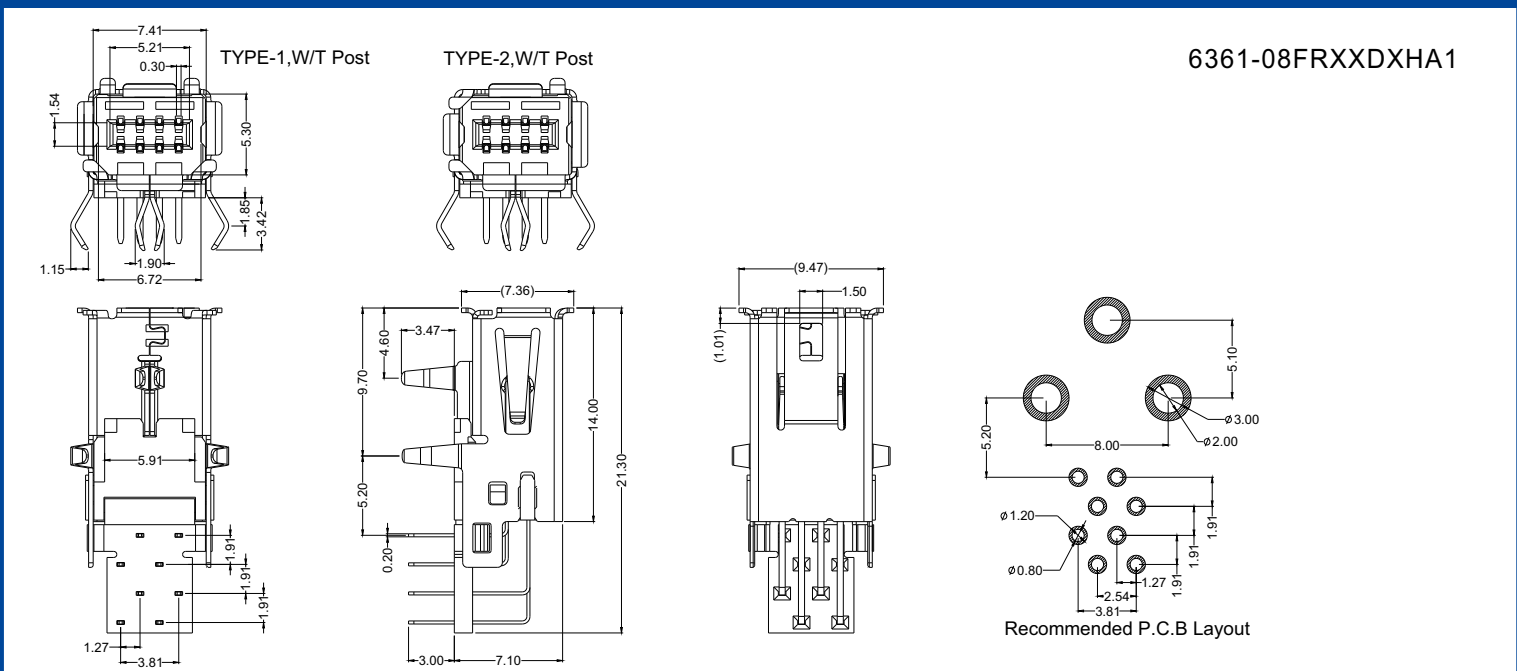
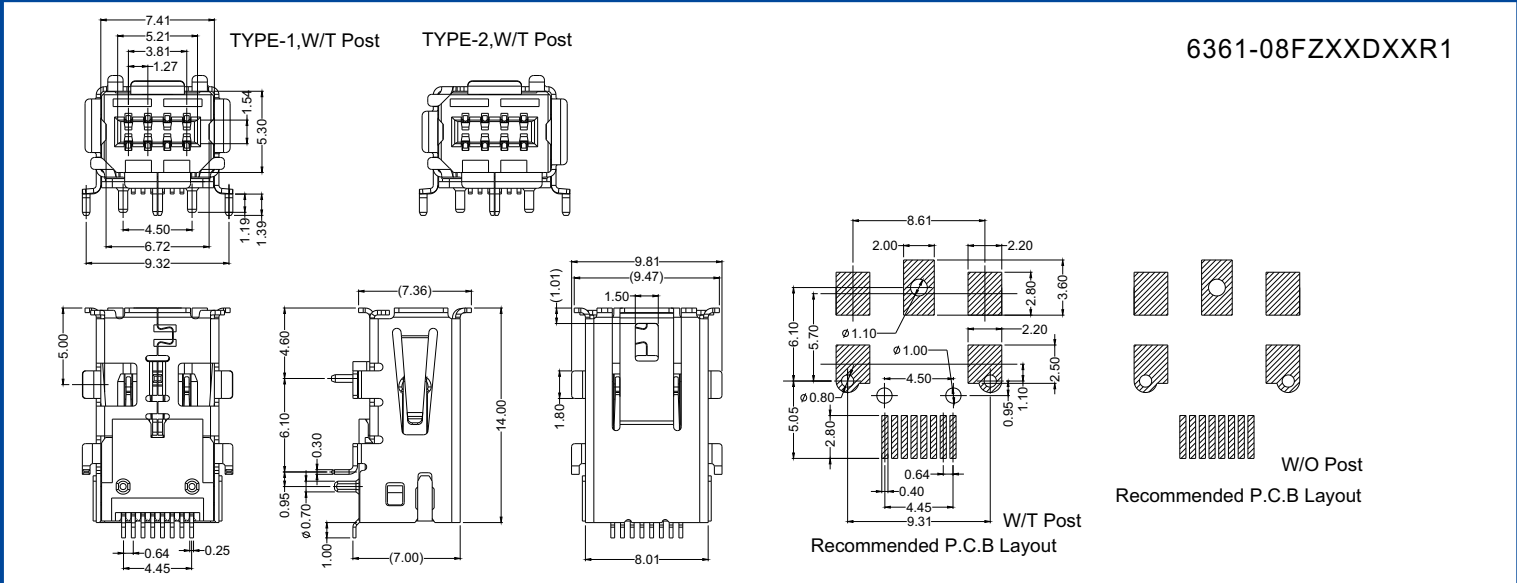


6361-08FZXDXXR1



6361-08FRXXDXHA1

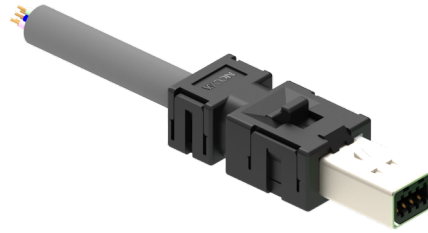
<b>6361</b>	<b>- 08</b>	<b>F</b>	<b>R</b>	<b>SX</b>	<b>D</b>	<b>X</b>	<b>H</b>	<b>A</b>	<b>1</b>
Positions 8	F:Female	Board-Mounting R:R/A DIP Z:R/A SMT	Contact plating area S4=15U" Au/Tin S5=30U" Au/Tin	Color B=Black T=Natural	Key Code W=TYPE 1,W/T Post N=TYPE 1,W/O Post M=TYPE 2,W/T Post H=TYPE 2,W/O Post	Packaging A=Tray R=Reel			





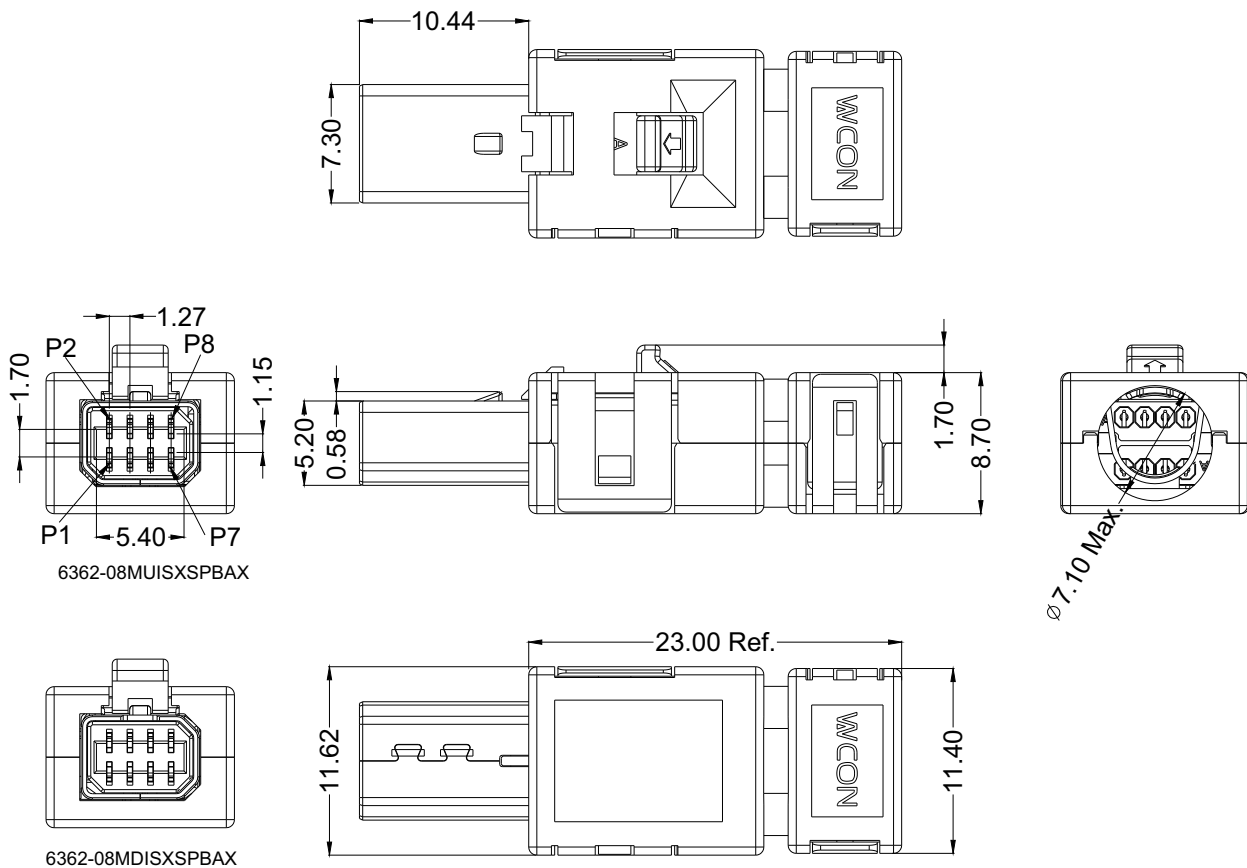
**SPECIFICATIONS**

Current Rating:0.5 AMP  
 Contact Resistance:40mΩ Max.  
 Insulation Resistance: 500MΩ Min  
 Withstand Voltage: 1000V AC/Minute  
 Operation Temperature: -40°C to +85°C  
 Contact Material:Copper Alloy  
 Contact Plating: Au And Sn Over Ni  
 Insulation Material:LCP+GF (UL94V-0)  
 Type:T



6362-08MXISXSPBAX

<b>6362</b>	<b>-</b>	<b>08</b>	<b>M</b>	<b>X</b>	<b>I</b>	<b>SX</b>	<b>S</b>	<b>P</b>	<b>B</b>	<b>A</b>	<b>1</b>
Positions 8			M:Male	Shape D:D Type U:U Type	Type Code: I=IDC Type	Contact plating area S4=15U" Au/Tin S5=30U" Au/Tin			Color: B=Black	Packaging A=Tray R=Reel	Internal Code 1:AWG24~22 2:AWG26~24 3:AWG28~26

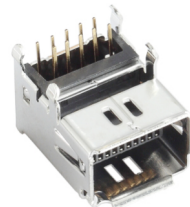


**SPECIFICATIONS**

Current Rating: 1.0 AMP  
 Contact Resistance: 50mΩ Max.  
 Insulation Resistance: 100MΩ Min  
 Withstand Voltage: 100V AC/Minute  
 Operation Temperature: -55°C to +105°C  
 Contact Material: Copper Alloy  
 Contact Plating: Au And Sn Over Ni  
 Insulation Material: PA9T+GF (UL94V-0)  
 Type: J

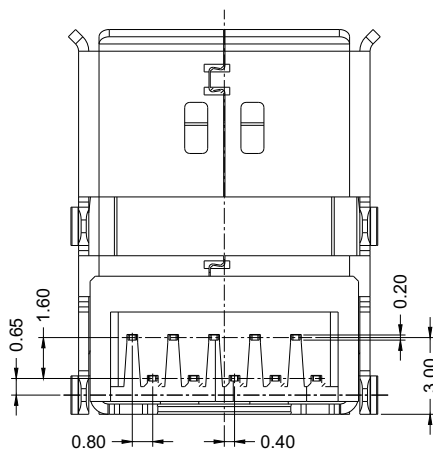
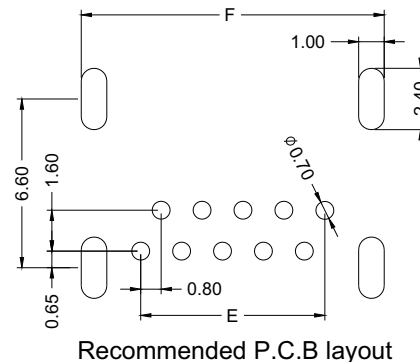
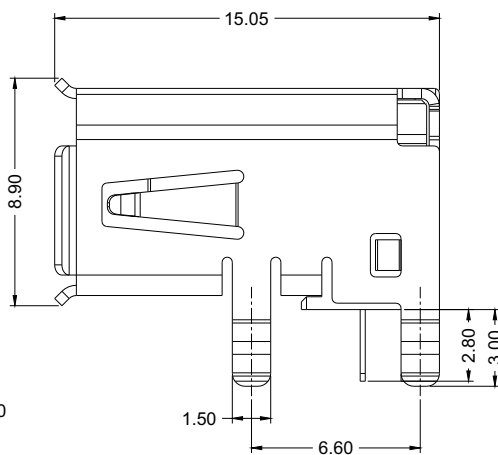
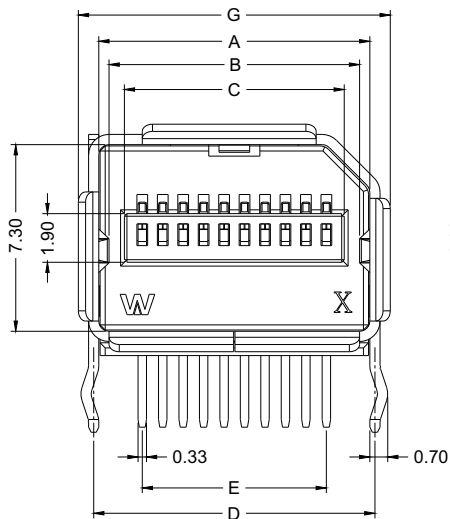


6363-08FRXXGBNR1



6363-10FRXXGBNR1

<b>6363</b>	<b>- 08</b>	<b>F</b>	<b>R</b>	<b>SX</b>	<b>G</b>	<b>B</b>	<b>N</b>	<b>R</b>	<b>1</b>
Positions 6, 8, 10		F: Female	Board-Mounting R: R/A DIP	Contact plating area S4=15U" Au/Tin S5=30U" Au/Tin		Color B=Black T=Natural	N=W/O Post W=W/T Post	Packaging R=Tape&Reel	



Pos	A	B	C	D	E	F	G
6	7.40	6.62	5.40	7.80	4.00	8.65	9.00
8	9.00	8.22	7.00	9.40	5.60	10.25	10.60
10	10.60	9.82	8.60	11.00	7.20	11.85	12.20

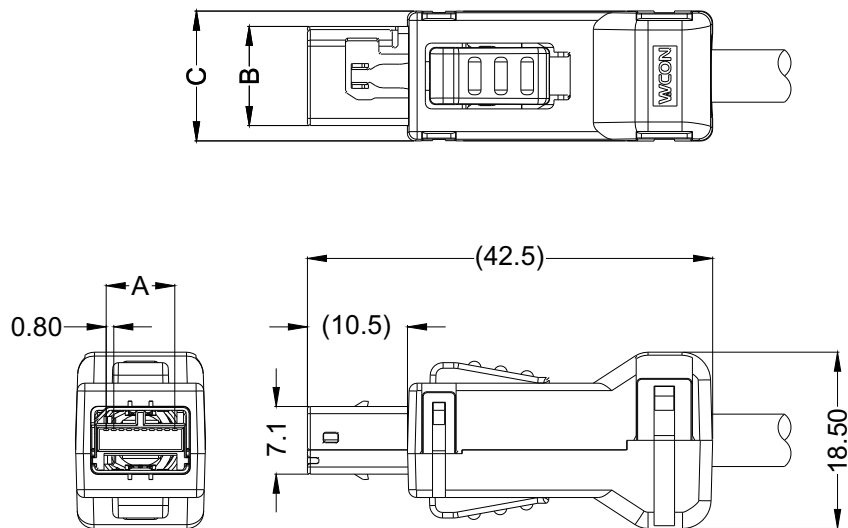
**SPECIFICATIONS**

Current Rating: 1.0 AMP  
 Contact Resistance: 50mΩ Max.  
 Insulation Resistance: 100MΩ Min  
 Withstand Voltage: 100V AC/Minute  
 Operation Temperature: -55°C to +85°C  
 Contact Material: Copper Alloy  
 Contact Plating: Au And Sn Over Ni  
 Insulation Material: PBT+GF (UL94V-0)  
 Type: J



6364-06MSHWXSCB01    6364-08MSHWXSCB01    6364-10MSHWXSCB01

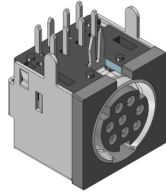
6364	-	<u>08</u>	<u>M</u>	<u>S</u>	<u>H</u>	<u>SX</u>	<u>S</u>	<u>P</u>	<u>B</u>	<u>0</u>	<u>1</u>
		Positions 6,8,10	M:Male			Contact plating area S4=15U" Au/Tin S5=30U" Au/Tin			Color: B=Black	Packaging O=PE Bag	Internal Code 1:AWG24~22 2:AWG26~24 3:AWG28~26



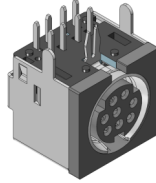
Pos	A	B	C
6	4.00	7.20	10.40
8	5.60	8.80	12.00
10	7.20	10.40	13.60

**SPECIFICATIONS**

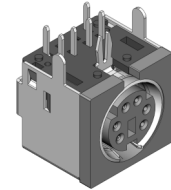
Current Rating:1.0 AMP  
 Contact Resistance:30mΩ Max.  
 Insulation Resistance: 100MΩ Min  
 Withstand Voltage: 500V AC/Minute  
 Operation Temperature: -55°C to +85°C  
 Contact Material:Phosphor Bronze  
 Contact Plating: Au And Sn Over Ni  
 Insulation Material:PA66 (UL94V-0)



6420 - 08 F S0 R B N 01



6421 - 08 F S0 R B N 01

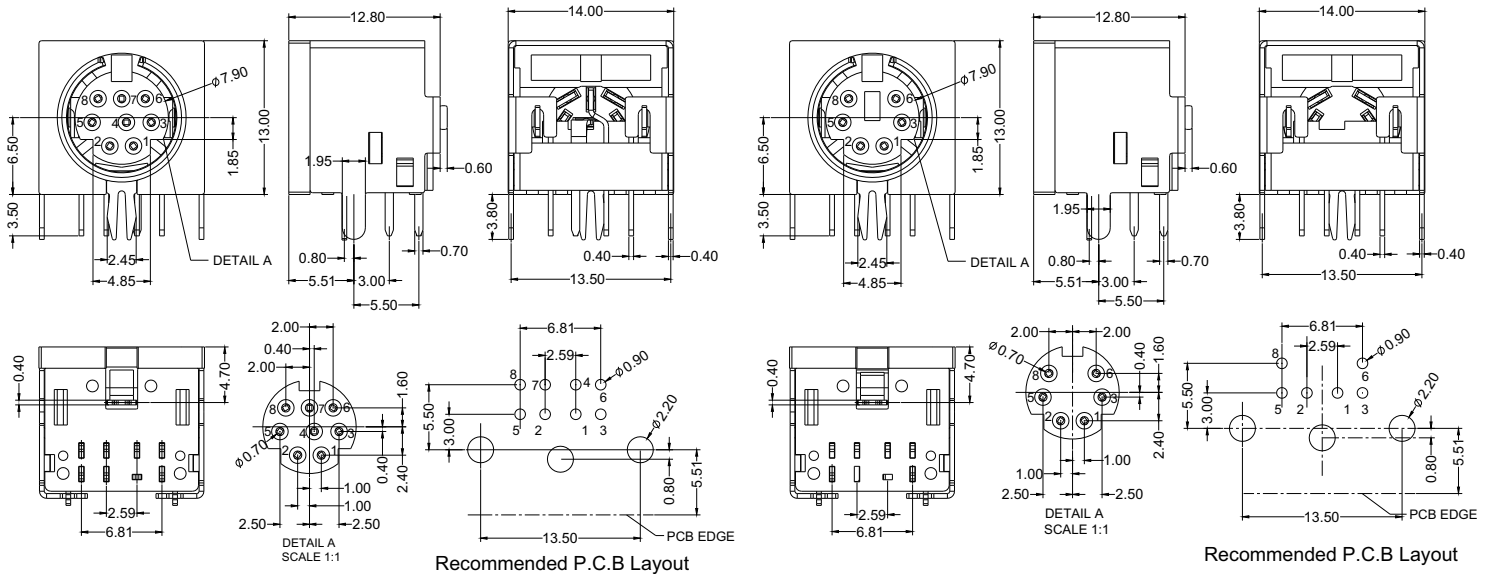


6421 - 06 F S0 R B N 01

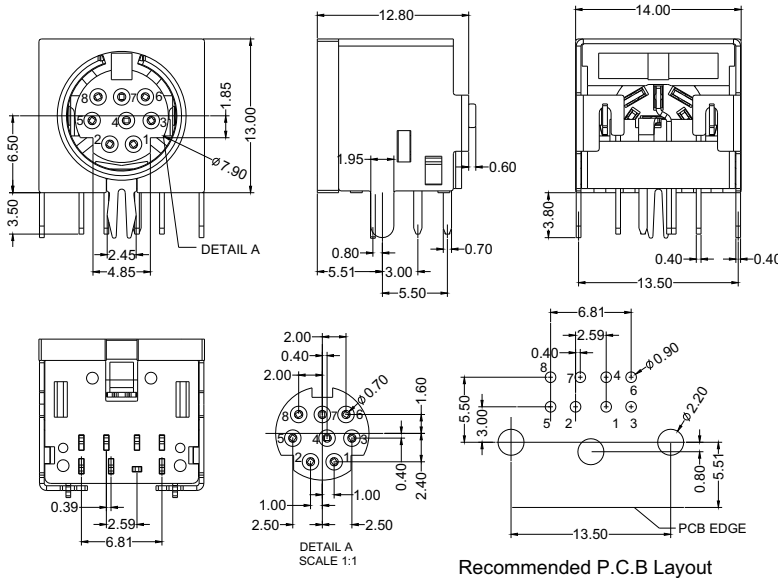
<b>6421</b>	<b>- XX</b>	<b>F</b>	<b>SX</b>	<b>R</b>	<b>B</b>	<b>N</b>	<b>A</b>	<b>1</b>
<b>6420</b>	Positions 6,8	F:Female	Contact plating area S0=Gold Flash/Tin S1=3U"Au/Tin	Board-Mounting R= R/A DIP			Packaging A=Tray	

6421 - 08 F S0 R B N 01

6421 - 06 F S0 R B N 01

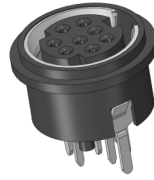


6420 - 08 F S0 R B N 01

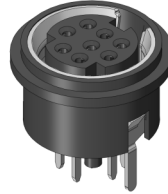


**SPECIFICATIONS**

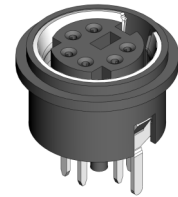
Current Rating:1.0 AMP  
 Contact Resistance:30mΩ Max.  
 Insulation Resistance: 100MΩ Min  
 Withstand Voltage: 500V AC/Minute  
 Operation Temperature: -55°C to +85°C  
 Contact Material:Phosphor Bronze  
 Contact Plating: Au And Sn Over Ni  
 Insulation Material:PA66 (UL94V-0)



6425 - 08 F S0 S B N 01



6424 - 08 F S0 S B N 01

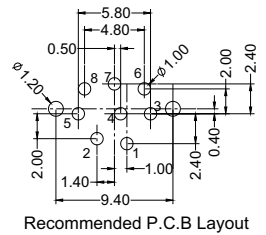
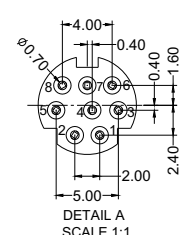
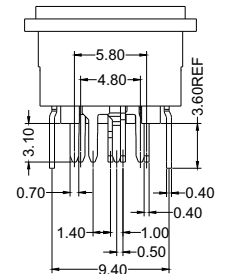
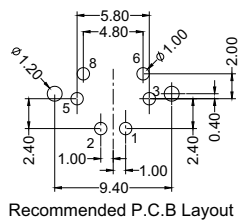
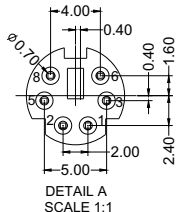
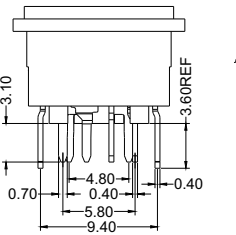
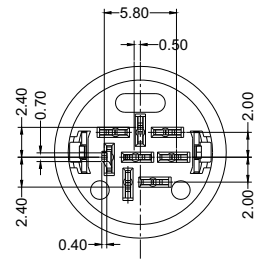
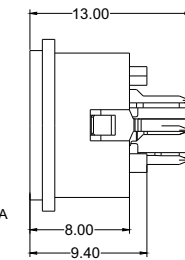
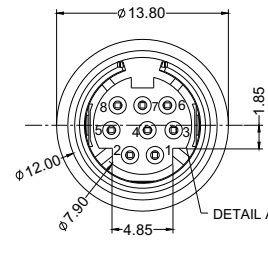
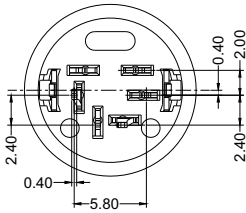
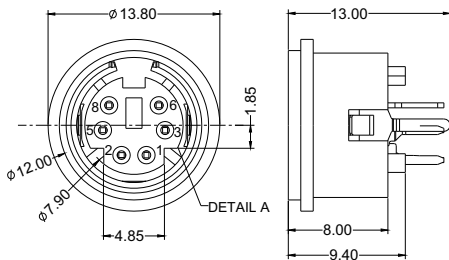


6424 - 06 F S0 S B N 01

<b>6424</b>	- <b>XX</b>	<b>F</b>	<b>SX</b>	<b>S</b>	<b>B</b>	<b>N</b>	<b>A</b>	<b>1</b>
<b>6425</b>	Positions 6,8	F:Female	Contact plating area S0=Gold Flash/Tin	Board-Mounting S=S/T DIP			Packaging A=Tray	

6424 - 06 F S0 S B N 01

6424 - 08 F S0 S B N 01



6425 - 08 F S0 S B N 01

